

TOPSELLER

Fully-Automatic BG Tape Laminator **RAD-3520F/12**



Multi-joint robotic arm



High throughput



Small foot print



Wide variety of optional functions



LINTEC Corporation

BENEFITS



Use of a multi-joint robotic arm

The multi-joint robotic arm offers versatile capabilities, allowing users to change the cutting angle & perform over, negative, and V-notch (optional) cutting with precision.



High throughput

Standard
specification

High speed
specification (optional)

Maximum UPH: 70

Maximum UPH: 100 *

*Capacity based on following conditions:

Wafer: 300 mm mirror polished wafer

Non-UV curable back-grinding tape: P-4140A from LINTEC



Small foot print

1,245mm(W) x 1,850mm(D) x 1,920mm(H)



A wide variety of optional functions

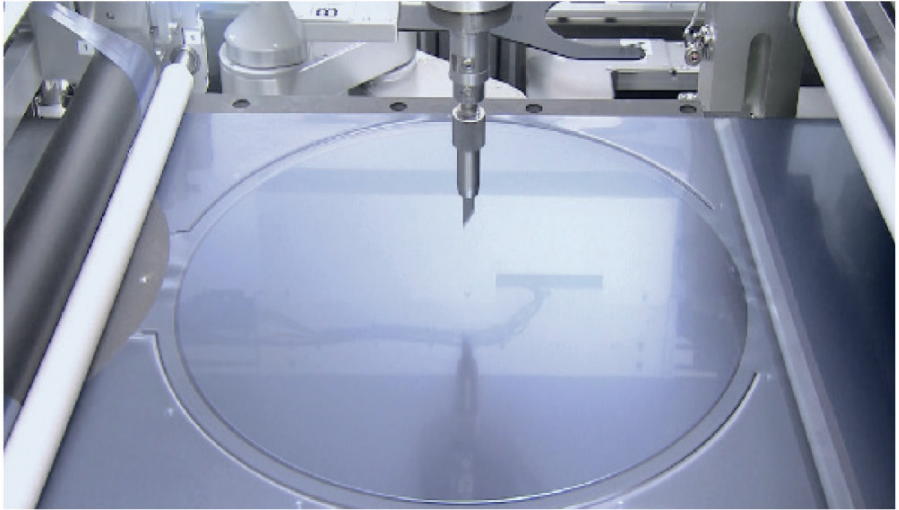
RAD-3520F/12 can be equipped with a wide range of optional functions to match specific customer requirements.



*High-precision
BG tape cutting
& lamination*

THREE-DIMENSION CUTTING

The multi-joint robotic arm ensures high-precision cutting with precise control of the cutter angle, resolving back-grinding issues caused by tape cutting burrs.



TAPE CUTTER EXCHANGE

The cutter blade can be automatically replaced by having the cutter blades readily available in a 12-blade magazine inside the machine.

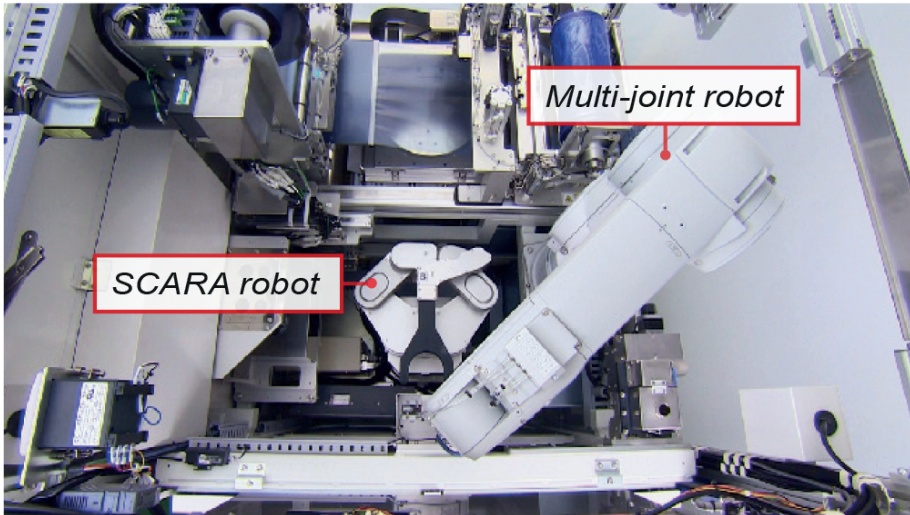


➔ *Reduces operator time and downtime for changing cutter blades.*

HIGH SPEED SPECIFICATION

A layout with two robots enables parallel processes for increased throughput.

- Wafer transfer & handling: SCARA robot
- Tape cutting: Multi-joint robot



CLEANING FUNCTION

Tape cutter cleaning

The use of two counter-rotating brushes enables the blade to be cleaned of adhesive residue that accumulates when cutting BG-tape. Regular cleaning of the blade ensures a consistently high cutting quality and extends the service life of the blade.

Wafer table cleaning

This feature enables particles to be removed from the attachment table before and/or after a wafer has been placed. The removal of particles before the lamination process prevents the occurrence of micro-cracks in the wafer and is particularly recommended for very thin or brittle material.

➡ *Reduces contamination and ensures consistently high cutting quality.*



STANDARD

- Non-contact alignment
- Three-dimensional cutting with multi-joint robot
- Double load-port
- FOUP opener with wafer mapping function
- Low-tension lamination by Tape Tension Control



OPTIONS

- High speed specification
- Automatic tape cutter exchange function
- Wafer table & tape cutter cleaning function
- Host communication function (SECS/GEM)
- Wafer ID reader
- ESD countermeasure specifications
- Warped wafer handling specification



Adwill

Tape x Equipment

Contact us.
We look forward
to meeting you!



LINTEC Advanced Technologies (Europe) GmbH

European Headquarters & Dresden office
Konrad-Zuse-Platz 1
81829 Munich
Germany

Phone: +49 (0)89 99 88 50 0

E-mail: sales@linceurope.com

www.linceurope.com

